

Please amend paragraph [0078] of the Substitute Specification as follows:

From each of the semiconductor polishing compounds obtained in Examples 1 to 4 and Comparative Example 1, 0.5 ml of the compound was extracted, and the number of fumed silica particles having a particle diameter of not smaller than 0.5 μm contained in each of the compounds was measured by use of a particle sizer (trade name: Accusizer 780 APS, manufactured by Particle Sizing Systems Inc.). The measurement was carried out twice.